



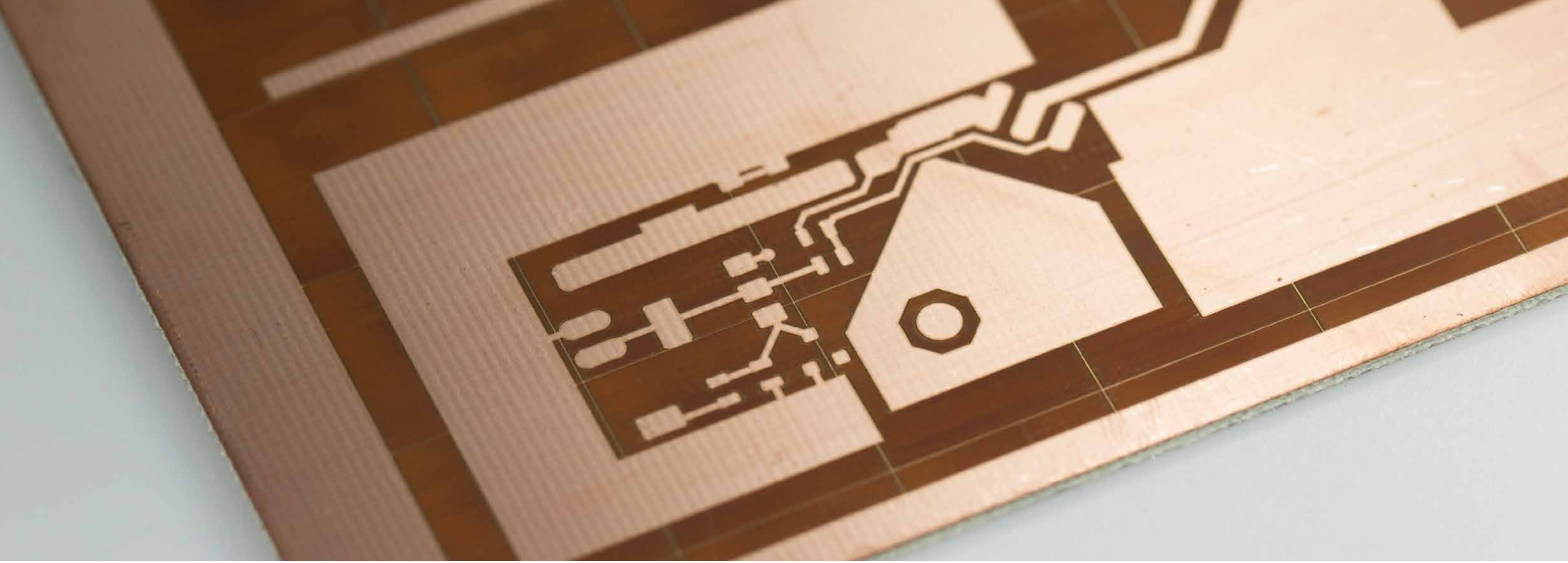
INNOLAS
solutions

INNOVATION FOR THE
NEXT GENERATION



ILS-ST SPLIT AXIS MACHINE

VERSATILE **LASER SYSTEM**
FOR MICRO MATERIAL PROCESSING

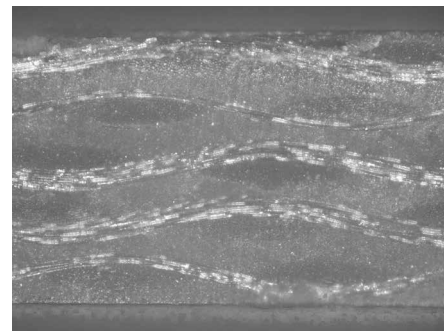
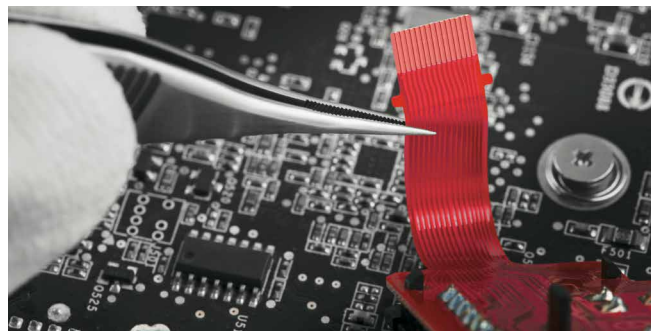
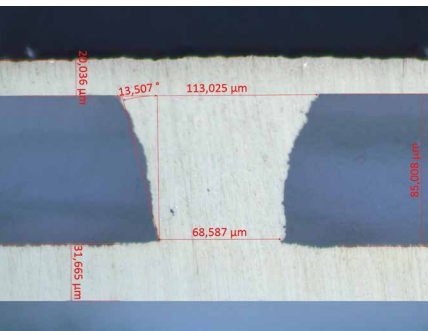


FEATURES

- ◆ Ultra fast laser technology
- ◆ Single or dual process head setup
- ◆ In-situ scanner calibration
- ◆ Double table option
- ◆ Processing one or more substrates in parallel
- ◆ Automatic laser to camera offset calibration
- ◆ Automated process controls
- ◆ Automated vision system for precision alignment and scaling, offset, trapezoidal and rotation compensation
- ◆ Stand alone or production line integrated system

OPTIONS

- ◆ Import of CAD files (e.g. DXF, DWG) and Excellon 2, Sieb & Meyer and Gerber file formats
- ◆ SQL data base for process and event tracking
- ◆ MES interface
- ◆ Integrated process metrology
- ◆ Semi-automatic handling (R&D)
- ◆ Fully-automatic handling (production)



APPLICATIONS

Micro Via Drilling, Routing, Depaneling, Micro Structuring, Selective Ablation, Cavity Formation

ACCURACY

< +/-10 μm abs.
< +/-2 μm repeatability

SUBSTRATES

Dimension up to 29.5" x 25" (750 mm x 635 mm)
Rigid-, flex-PCBs, ceramic, glass and advanced materials

AVAILABLE LASER SOURCES

Wavelength: 9.4, 10.6 μm (CO₂), 1064, 1030, 532, 515, 355 nm
Pulse: μs, ns, ps, fs

DIMENSIONS

1750 x 2200 x 2600 mm

